

TITLE: METHODS FOR DETERMINING AMOUNTS AND LOCATIONS OF
DIFFERENTIAL PRESSURE TO BE APPLIED TO SEMICONDUCTOR SUBSTRATES
DURING POLISHING OF SEMICONDUCTOR DEVICE STRUCTURES CARRIED
THEREBY AND FOR SUBSEQUENTLY POLISHING SIMILAR SEMICONDUCTOR
DEVICE STRUCTURES
Inventor: Nathan R. Brown
Docket No.: 2269-4375.1US

1/7

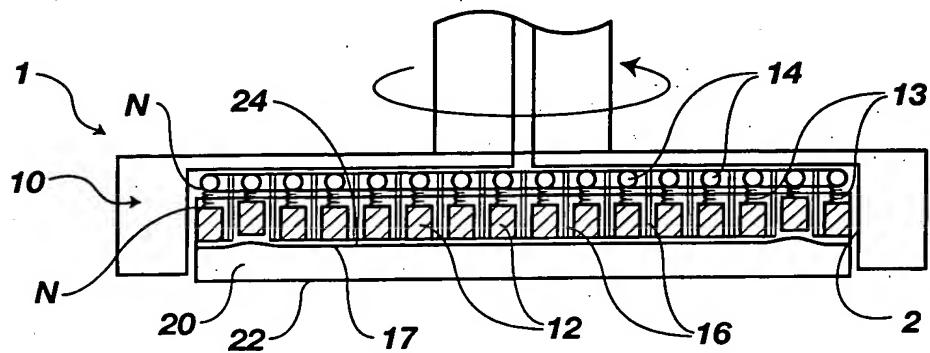


FIG. 1

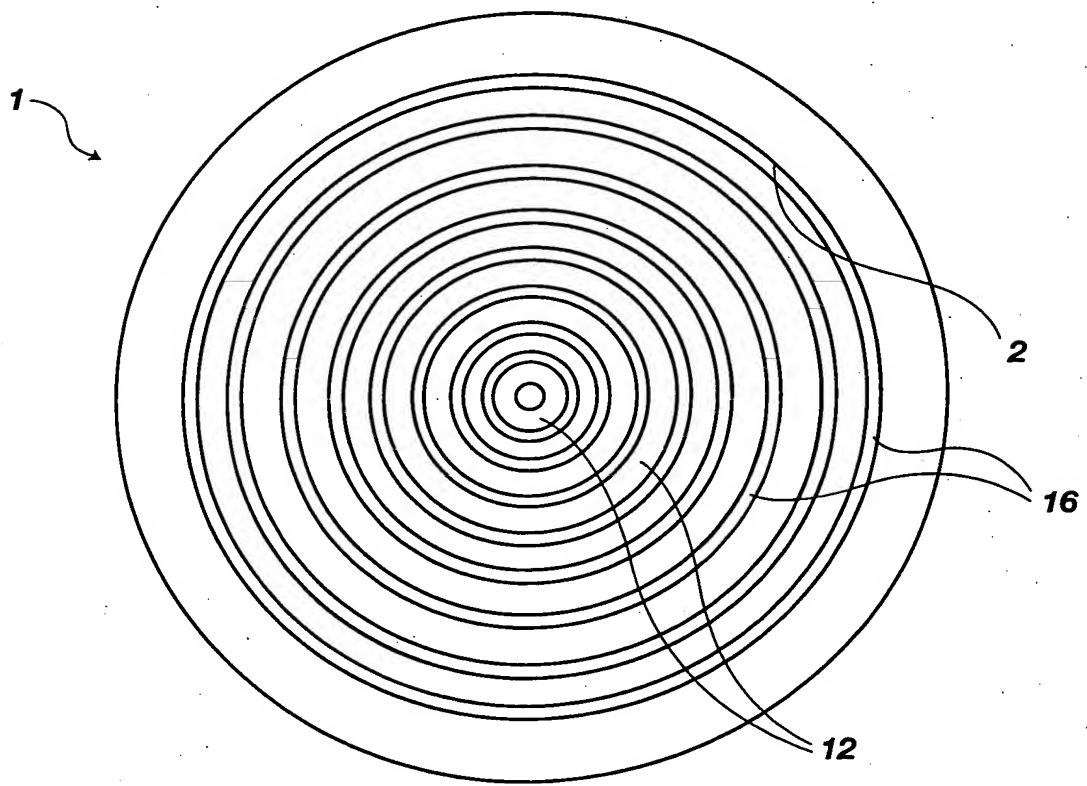


FIG. 2

TITLE: METHODS FOR DETERMINING AMOUNTS AND LOCATIONS OF DIFFERENTIAL PRESSURE TO BE APPLIED TO SEMICONDUCTOR SUBSTRATES DURING POLISHING OF SEMICONDUCTOR DEVICE STRUCTURES CARRIED THEREBY AND FOR SUBSEQUENTLY POLISHING SIMILAR SEMICONDUCTOR DEVICE STRUCTURES
Inventor: Nathan R. Brown
Docket No.: 2269-4375.1US

2/7

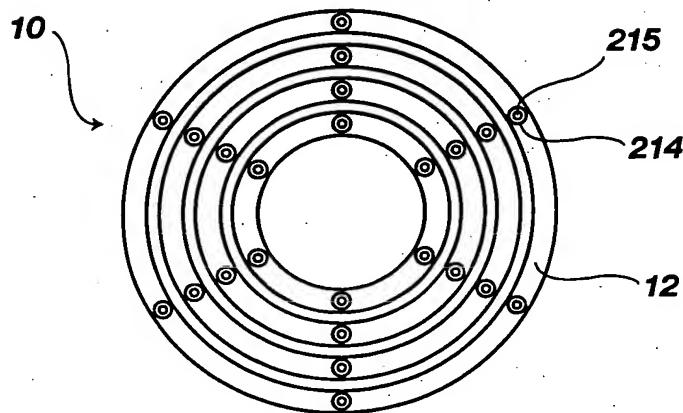


FIG. 1A

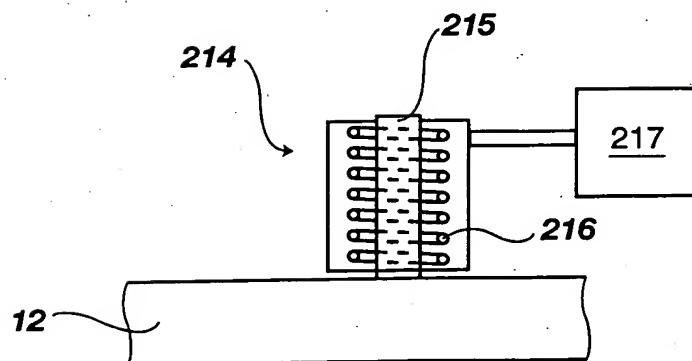


FIG. 1B

3/7

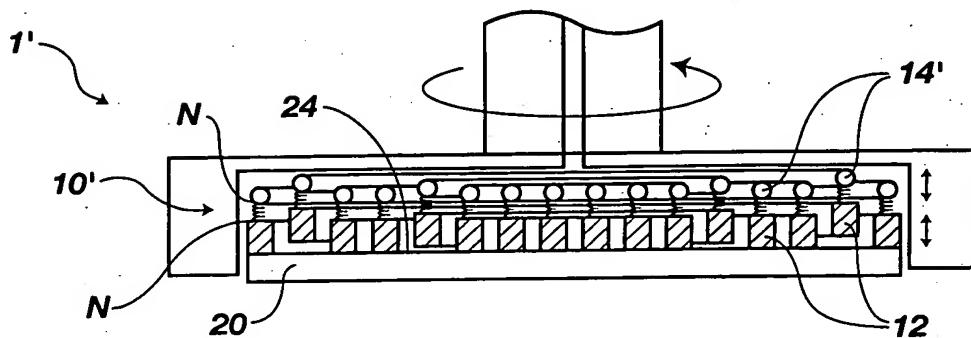


FIG. 3

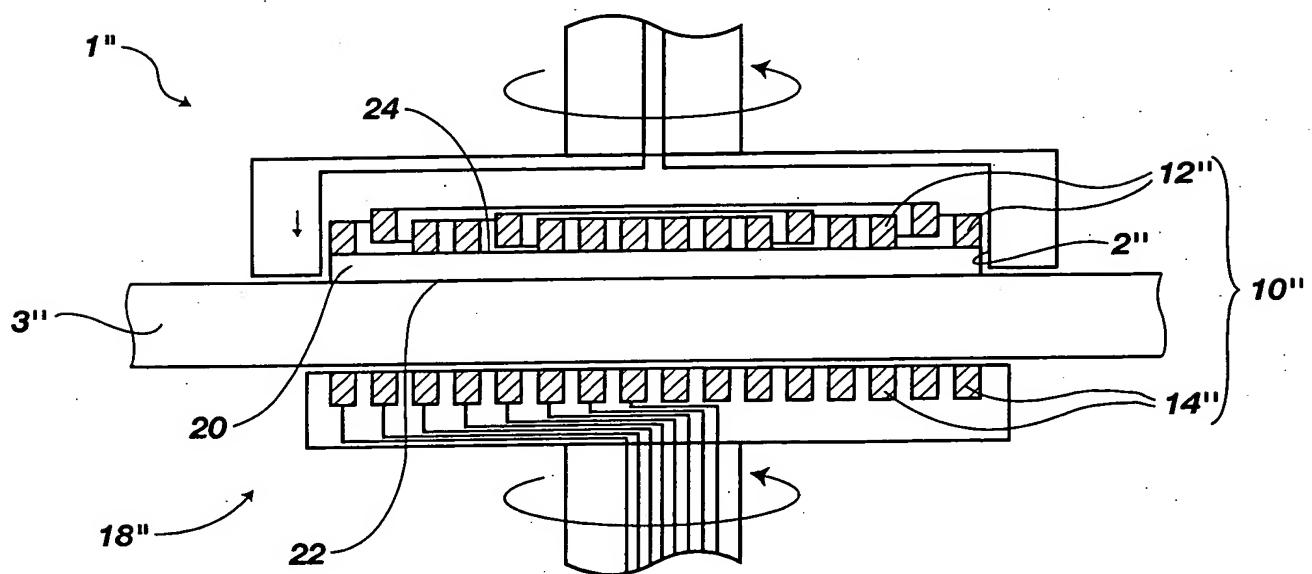


FIG. 4

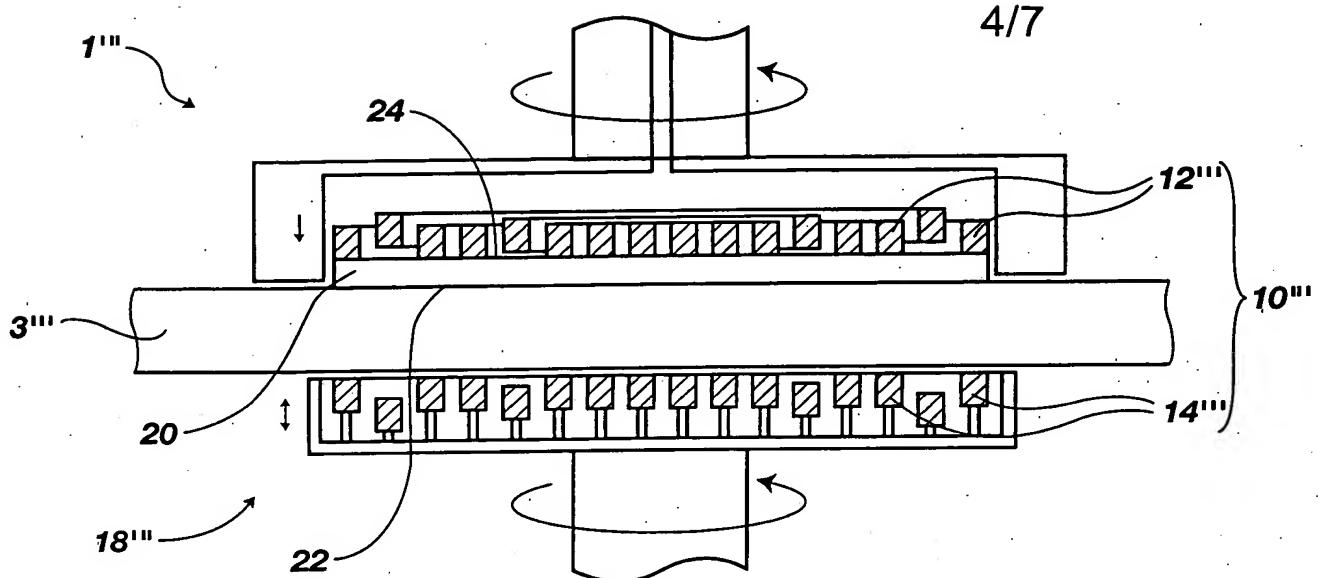


FIG. 5

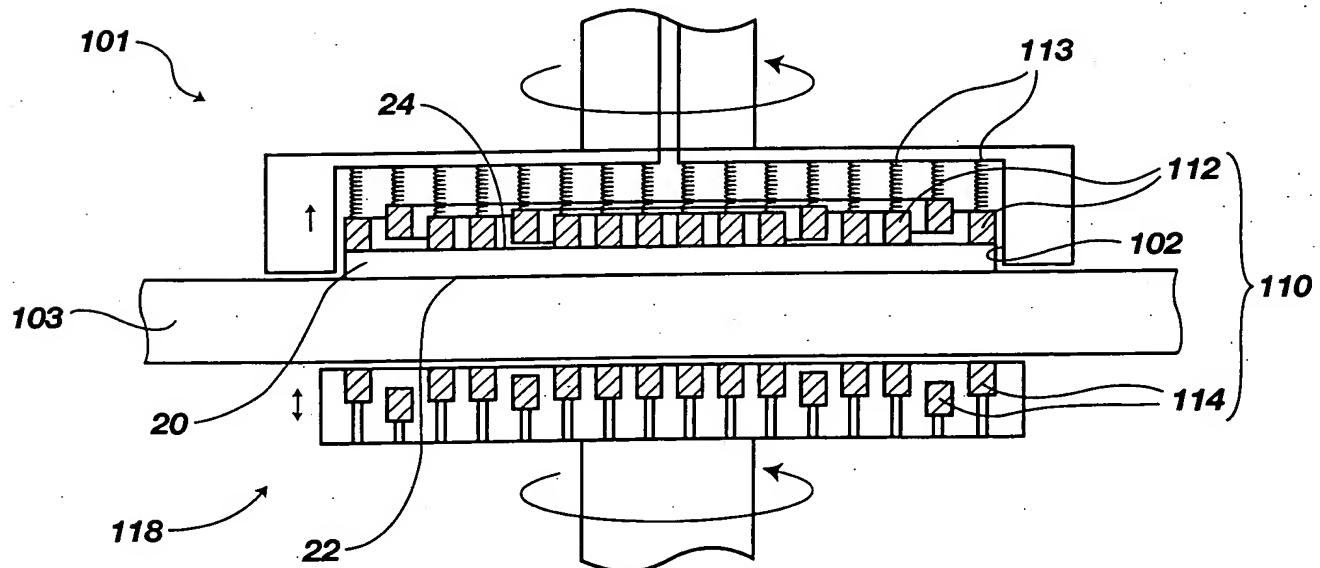


FIG. 6

5/7

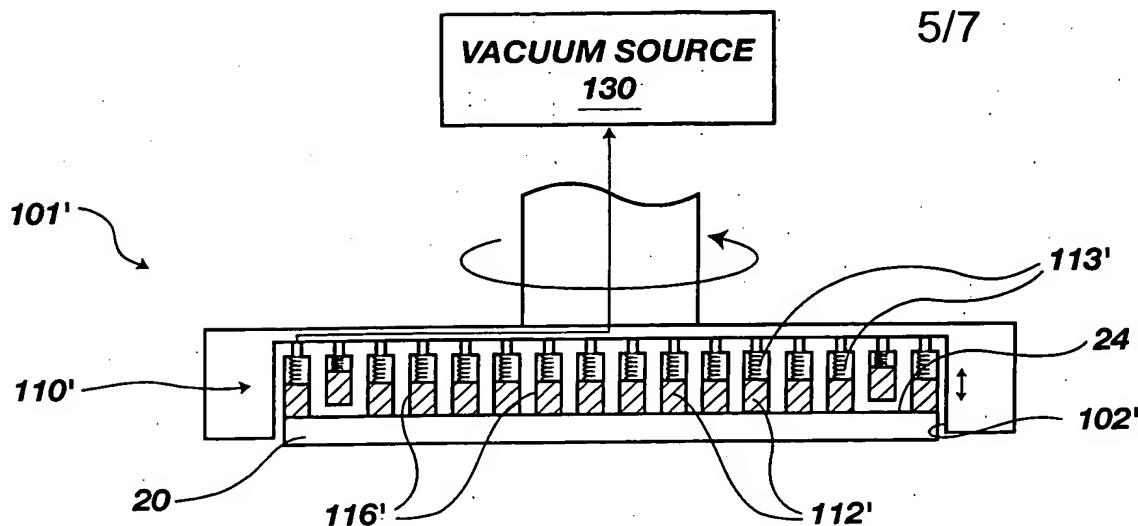


FIG. 7

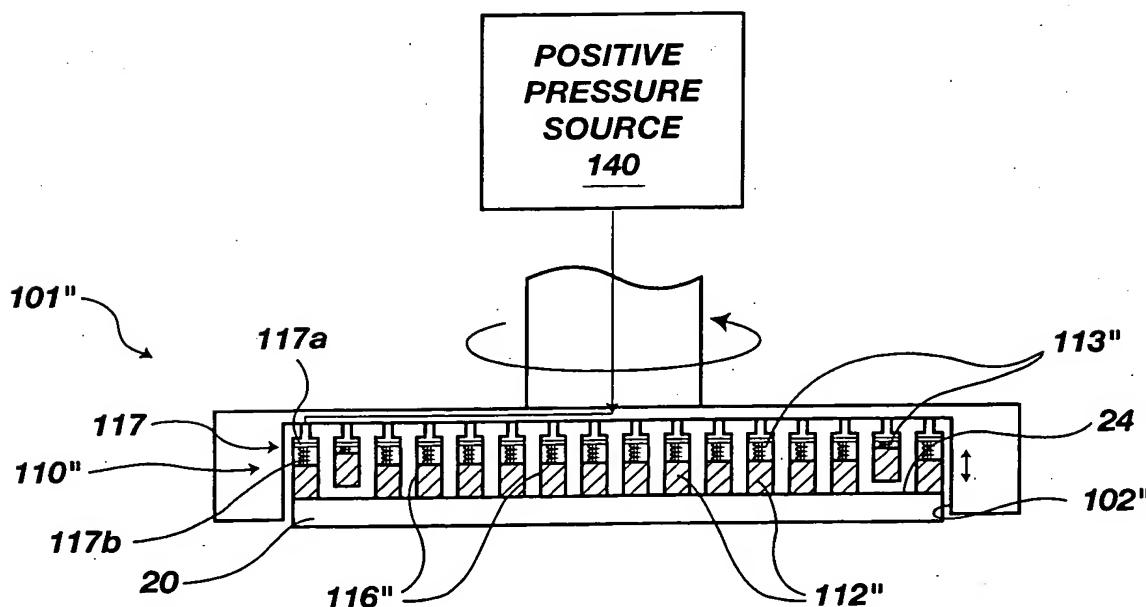


FIG. 8

TITLE: METHODS FOR DETERMINING AMOUNTS AND LOCATIONS OF
DIFFERENTIAL PRESSURE TO BE APPLIED TO SEMICONDUCTOR SUBSTRATES
DURING POLISHING OF SEMICONDUCTOR DEVICE STRUCTURES CARRIED
THEREBY AND FOR SUBSEQUENTLY POLISHING SIMILAR SEMICONDUCTOR
DEVICE STRUCTURES
Inventor: Nathan R. Brown
Docket No.: 2269-4375.1US

6/7

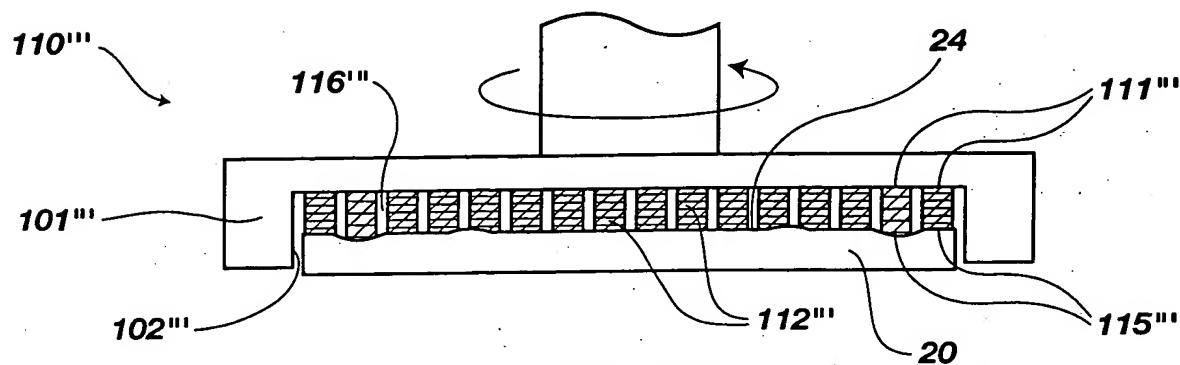


FIG. 9A

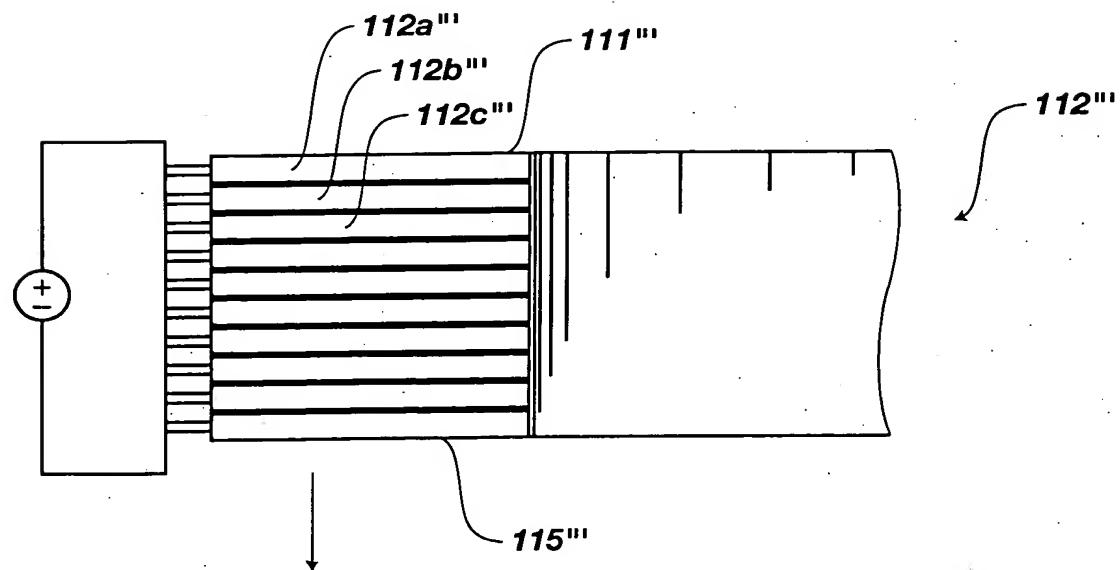


FIG. 9B

TITLE: METHODS FOR DETERMINING AMOUNTS AND LOCATIONS OF
DIFFERENTIAL PRESSURE TO BE APPLIED TO SEMICONDUCTOR SUBSTRATES
DURING POLISHING OF SEMICONDUCTOR DEVICE STRUCTURES CARRIED
THEREBY AND FOR SUBSEQUENTLY POLISHING SIMILAR SEMICONDUCTOR
DEVICE STRUCTURES
Inventor: Nathan R. Brown
Docket No.: 2269-4375.1US

7/7

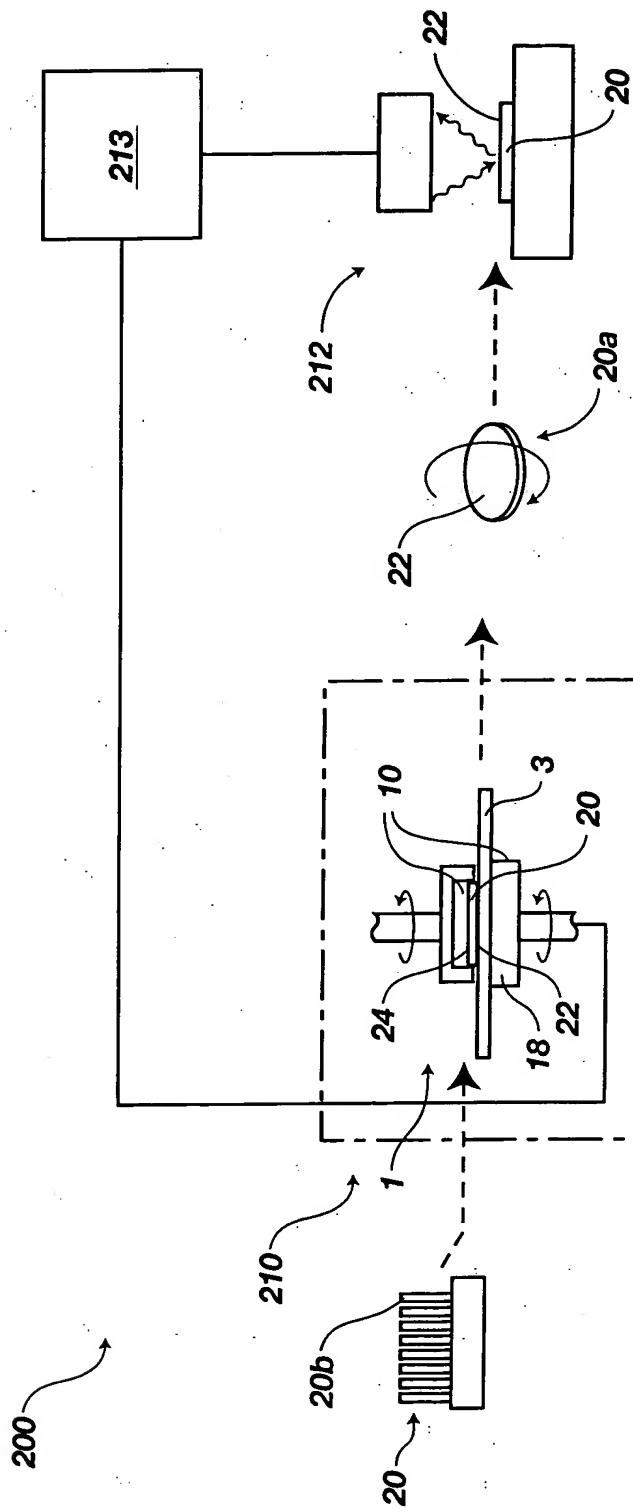


FIG. 10